

L Number	Hits	Search Text	DB	Time stamp
1	17948	tether\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:07
2	1736	tether\$2 and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:10
3	1	("5472085").PN.	USPAT	2003/03/04 12:32
4	1	("6179127").PN.	USPAT	2003/03/04 12:25
5	1098	(chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:36
6	324	((chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole)) ) and((substrate or carrier or support or wafer) near (semiconductor or silicon or si or GA\$2 or (gallium adj arsenide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:41
7	0	((chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole)) ) and((substrate or carrier or support or wafer) near (semiconductor or silicon or si or GA\$2 or (gallium adj arsenide))) ) and tether\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:40
8	0	((chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole)) ) and tether\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:40
9	1736	tether\$2 and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:40
10	1461	(tether\$2 and (chip or die)) and(substrate or carrier or support or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:41
11	371	(tether\$2 and (chip or die)) and ((substrate or carrier or support or wafer)with (silicon or ga\$2 or si))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:48
12	4387	206/\$.ccls. and (chip or die or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:52
13	114	206/\$.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:15
14	8	206/710.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18
15	0	206/7111.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:17

16	0	206/711.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18
17	0	206/711.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18
18	568	257/668.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18